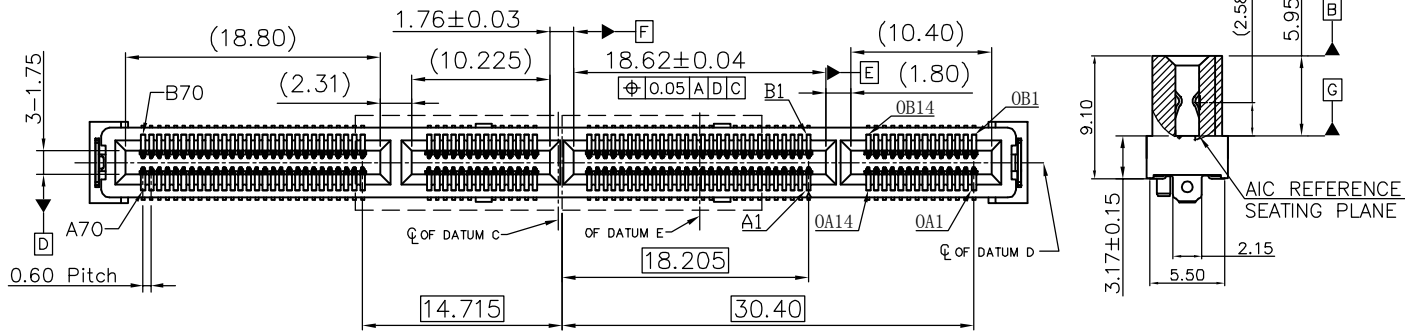
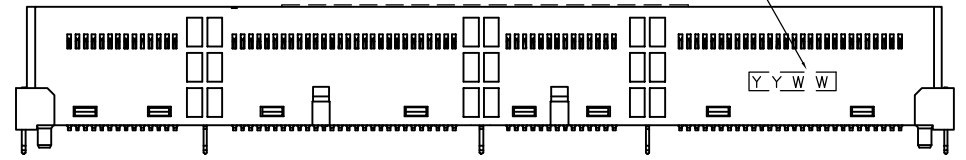
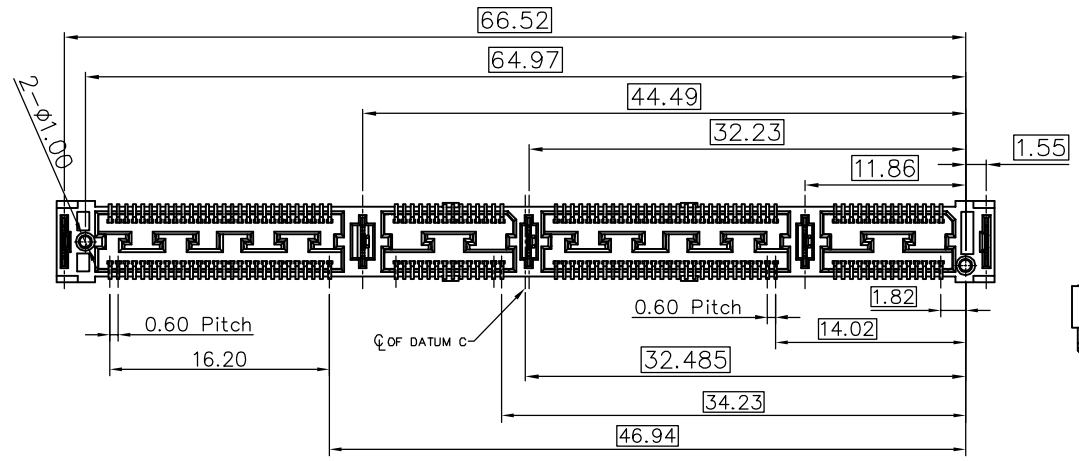
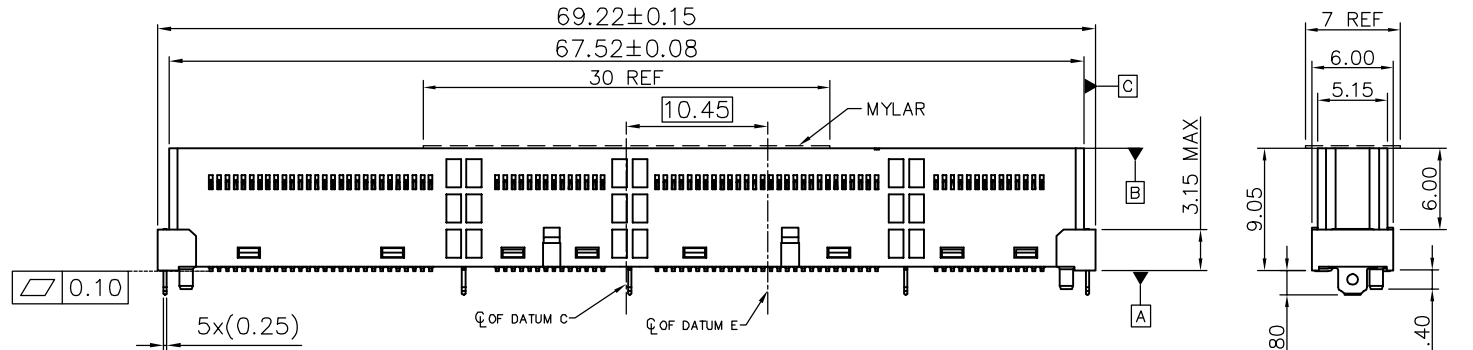


REV.	ECN.NO.	MODIFY.CONTENT
X1	2022-04-28	NEW
X2	2023-06-25	Update drawings
X3	2023-10-25	Update drawings



NOTES:
 1 MATERIAL:
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC 94V-0, BLACK COLOR
 TERMINAL: COPPER ALLOY
 BOARD LOCK: COPPER ALLOY
 2 PLATING:
 TERMINAL:
 SELECTIVE Au (SEE ORDER INFORMATION) ON CONTACT AREA,
 MATTE TIN ON SOLDER TAIL AREA, BOTH OVER Ni UNDERPLATED.
 3 THIS LAYOUT REFER TO THE SPECIFICATION OPC-NIC 3.0
 4 MECHANICAL CHARACTERISTICS
 4.1 MATING FORCE (MODULE TO CONNECTOR)
 168PIN 4C+ = 92.4 N MAX.
 4.2 MATING UNMATING FORCE
 168PIN 4C+ = 8.4 N MIN.
 4.3 DURABILITY: 200 CYCLES.
 5 ELECTRICAL CHARACTERISTICS
 5.1 CONTACT CURRENT RATING: 1.1AMPS . PER PIN.
 5.2 INSULATION RESISTANCE: 1000 MEGOHMS
 5.3 DIELECTRIC WITHSTANDING VOLTAGE:300 VAC CURRENT
 LEAKAGE:0.5mA MAX
 5.4 LOW LEVEL CONTACT RESISTANCE:
 INITIAL:30 MILLIOHMS MAX, DELTA:15 MILLIOHMS MAX.
 6 OPERATING TEMPERATURE RANGE: -40°C TO +85°C .
 7 THE PRODUCT DRAWING PER SFF-TA-1002 Rev:1.2
 8 ORDER INFORMATION:
 GENZ-*** L * * 1 **
 168:168Pin
 0: WITH LOGO
 1: WITHOUT LOGO
 0: TAPE REEL
 1: TRAY
 46: Au15u"/Sn80u"/Ni50u"
 47: Au30u"/Sn80u"/Ni50u"
 1: TYPE A



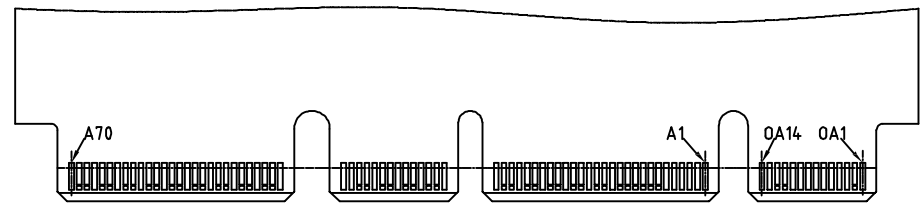
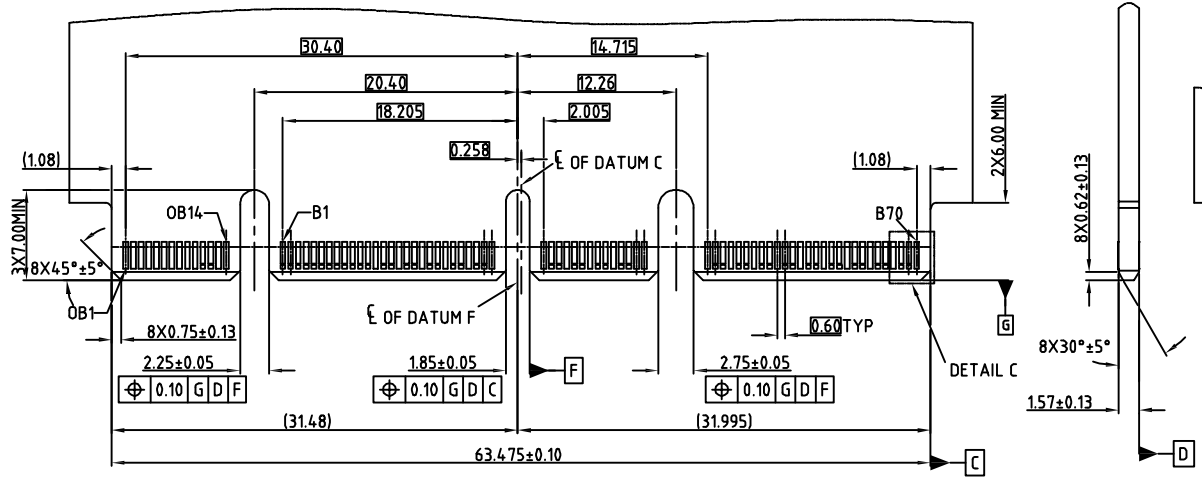
印字周期:
 年年周期

GENERAL	TOLERANCE	DWG.NO.	GENZ-168L10100	PART.NO.	GENZ-168L101XX	DRAWN	TONY 2023-06-25
x.±0.50	x.±5°	REV.	X3	TITLE	GEN Z 4C+ (SFF TA-1002)	CHECKED	
.x±0.25	.x±2°	SIZE	A4	SHEET	1 OF 3	APPROVED	
.xx±0.15	.xx±1°						

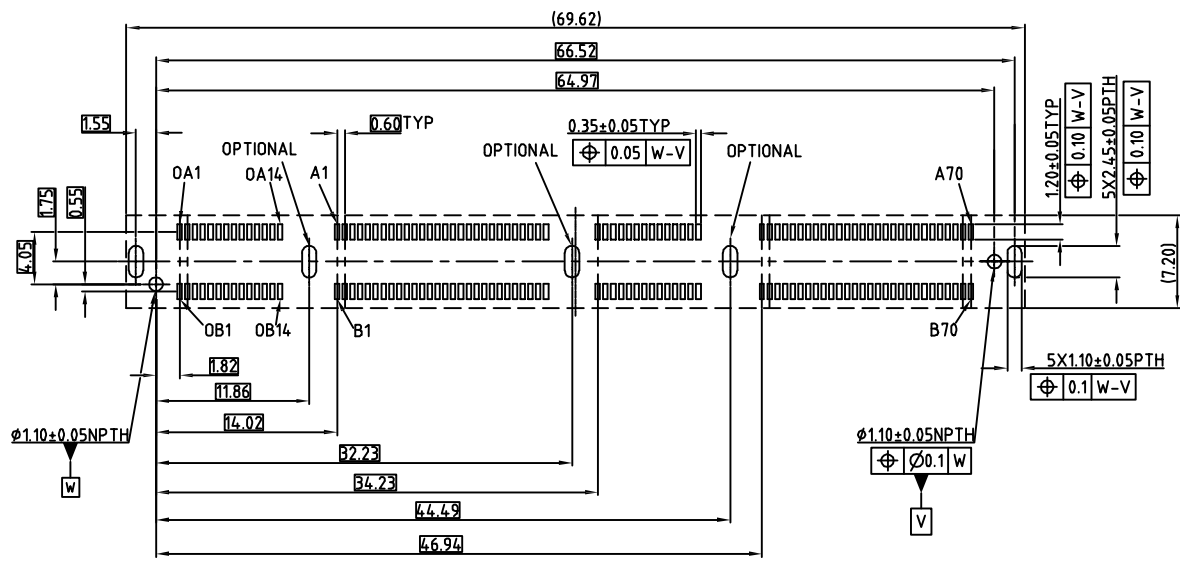
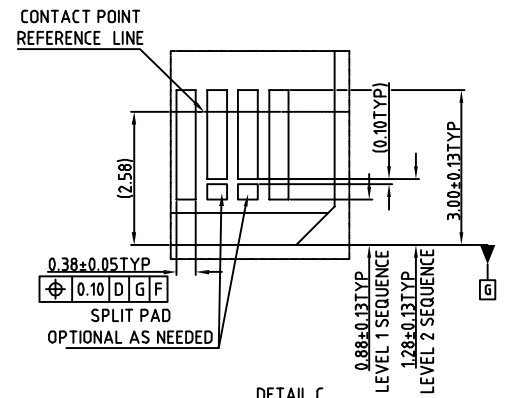
UNIT mm SCALE 1:1

OLN 东莞市欧联电子科技有限公司
 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.

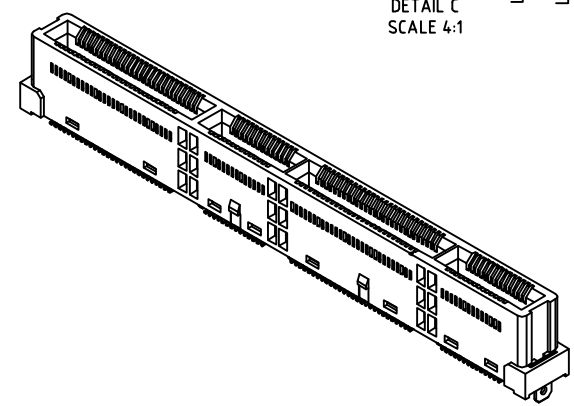
REV.	ECN.NO.	MODIFY.CONTENT
X1	2022-04-28	NEW
X2	2023-06-25	Update drawings
X3	2023-10-25	Update drawings



RECOMMENDED AIC MATING CARD



RECOMMENDED FOOTPRINT



GENERAL TOLERANCE	DWG.NO.	GENZ-168L10100	PART.NO.	GENZ-168L101XX	DRAWN	TONY 2023-06-25
x.±0.50	REV.	X3	TITLE	GEN Z 4C+ (SFF TA-1002)	CHECKED	
.x±0.25	SIZE	A4	SHEET	2 OF 3	APPROVED	
.xx±0.15						

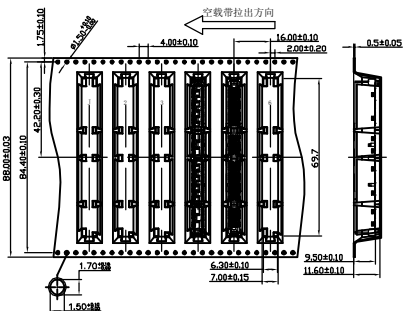
UNIT mm SCALE 1:1

OLN 东莞市欧联电子科技有限公司
DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.

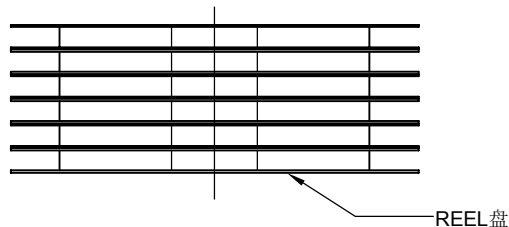
REV.	ECN.NO.	MODIFY.CONTENT
X1	2022-04-28	NEW
X2	2023-06-25	Update drawings
X3	2023-10-25	Update drawings

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

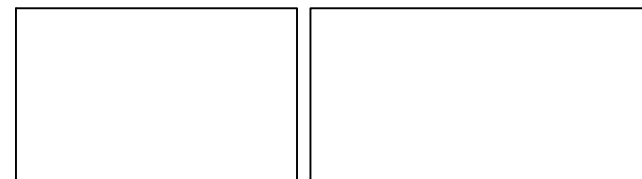
- 一. 1) 将成品一一放入REEL包装盘内,依同一方向放入
 2) 包装时,如图所示.
 3) 一个REEL包装盘放置300个成品.



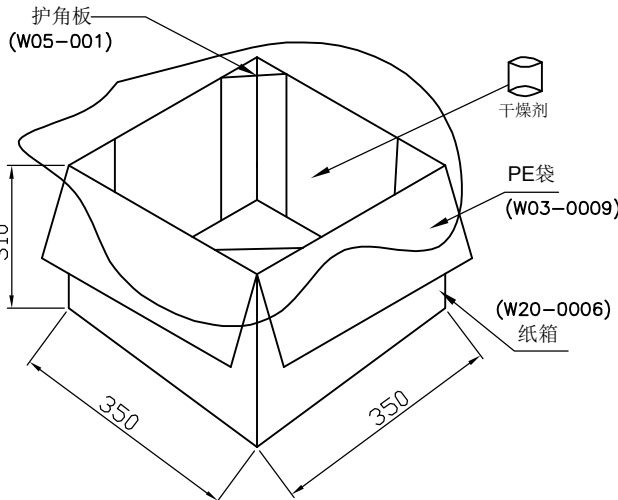
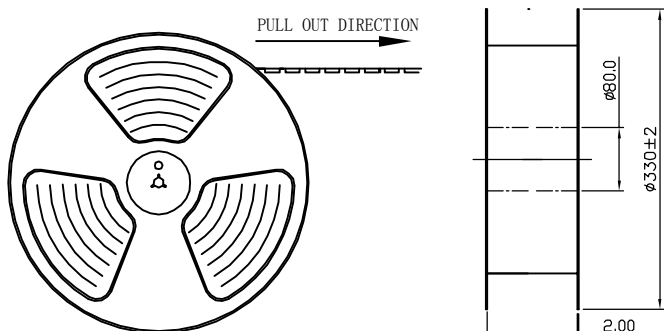
- 三. 1) 每箱装 3 盘REEL包装盘.
 2) 每箱放置 900 PCS 的成品.



- 四. 1) 用TAPE將紙箱封實.



- 二. 1) 装盘前先把前面空15pcs产品,然后再开始装盘, 尾端也需空15pcs产品,上带加长200mm.
 2) 装满成品的REEL包装盘如下图所示.



備註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿.

GENERAL TOLERANCE	TOLERANCE	DWG.NO.	GENZ-168L10100	PART.NO.	GENZ-168L101XX	DRAWN	Tony 2023-07-14
x. \pm 0.50	x. \pm 5'	REV.	X3	TITLE	GEN Z 4C+ (SFP TA-1002)	CHECKED	
.x \pm 0.25	.x \pm 2'	SIZE		SHEET	3 OF 3	APPROVED	
.xx \pm 0.15	.xx \pm 1'	A4					

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			